

VHF Chokes

Material Data Sheet

Product Class:	Cylinder Core Chokes B82111E0000C0**
Date	25.04.2013
IMDS ID	
if available	
Version:	10



Product Part (IMDS: semi component)	Material Class (IMDS: Material)	Material (Classification) VDA 231	Substance	TMPS**) [wt%]	CAS if applicable	typical mass of material [wt-%]	Traces see 1)
Active Part	Ceramic	4B	Nickel Zinc Ferrite	100	12645-50-0	68.7	
	Heavy Metal	1C	Cu	100	7440-50-8	12.9	
	Elastomer	2B	Polyurethane (PUR)	100	68400-67-9	0.7	
Encapsulation and Mounting	Thermoplastic	2A	Polyethylene Terephthalate (PET)	100	25038-59-9	2.6	
	Heavy Metal		Pb	94	7439-92-1	0.4	
		1C	Sn	5	7440-31-5		
			Ag	1	7440-22-4		
	Heavy Metal	1C	Sn forC029,C020	100	7440-31-5		
Termination ***)	Heavy Metal	1C	Cu	100	7440-50-8	14.5	
	Heavy Metal	1C	Sn	100	7440-31-5	0.2	
	•		•		Sum in total:	100.0	•

Size Ø x L [max. in mm] 7.5 x 26 7.5 x 26 7.0 x 26 7.0 x 26	Weight [approx. in g] 3.6 3.2 3.0 3.3	Part Numbers B82111E0000C020 B82111E0000C021 B82111E0000C022 B82111E0000C023	Size Ø x L [max. in mm] 6.5 x 26 6.5 x 26 6.0 x 26 6.0 x 26	Weight [approx. in g] 2.5 2.3 2.2 2.2	Part Numbers B82111E0000C025 B82111E0000C026 B82111E0000C027 B82111E0000C028	
6.5 x 26	3.3 2.3	B82111E0000C023	6.0 x 26	2.2	B82111E0000C029	

Not part of a Product Class ____

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^{*)} others: not declarable or prohibited substances acc. GADSL

Important remarks:

The declaration limit is 0.1% as defined by IEC 62474 (IEC PAS 61906) Traces are product parts, substances etc. that are below a percentage of 0.1 % by weight, if not otherwise regulated

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The products set forth herein are "RoHS-compatible". RoHS-compatible means that products are compatible with the requirements according to Art. 4 (substance restrictions) of Directive 2011/65/EU of the European Parliament and of the Council of June 8th, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment.

RoHS - Exemptions for the Product Class / Product according to Annex III: (☑ valid ☐ not valid))

□ no exemptions;

□ Exemption 6 (a): Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0,35 % lead by weight;

 \square Exemption 6 (b): Lead as an alloying element in aluminium containing up to 0,4 % lead by weight;

☐ Exemption 6 (c): Copper alloy containing up to 4 % lead by weight;

☑ Exemption 7 (a): Lead in high melting temperature type solder (i.e. lead-based alloys containing 85 % by weight or more lead);

□ Exemption 7 (c)-1: Electrical and electronic components containing lead in a glass or ceramic other than dielectric ceramic in capacitors, e.g. piezoelectronic devices, or in a glass or ceramic matrix compound;

☐ Exemption 7 (c)-II: Lead in dielectric ceramic in capacitors for a rated voltage of 125 V AC or 250 V DC or higher;

□ Exemption 7 (c)-III: Lead in dielectric ceramic in capacitors for a rated voltage of less than 125 V AC or 250 V DC;

🗆 Exemption 15: Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages;

☐ Other Exemption than above

 $\ensuremath{\square}$ no exemptions; for B82111E0000C020, B82111E0000C029,

^{**)} typical mass percentage of substance

^{***)} lead from high temperature solder can be found on pins in a certain distance from core flange